

STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower

MB1848_HP

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Sheet 1: Project overview (this page)

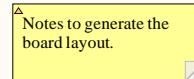
Sheet 2: Reference_Design_STM32WL_4L_IPD_ST_HP.SchDoc

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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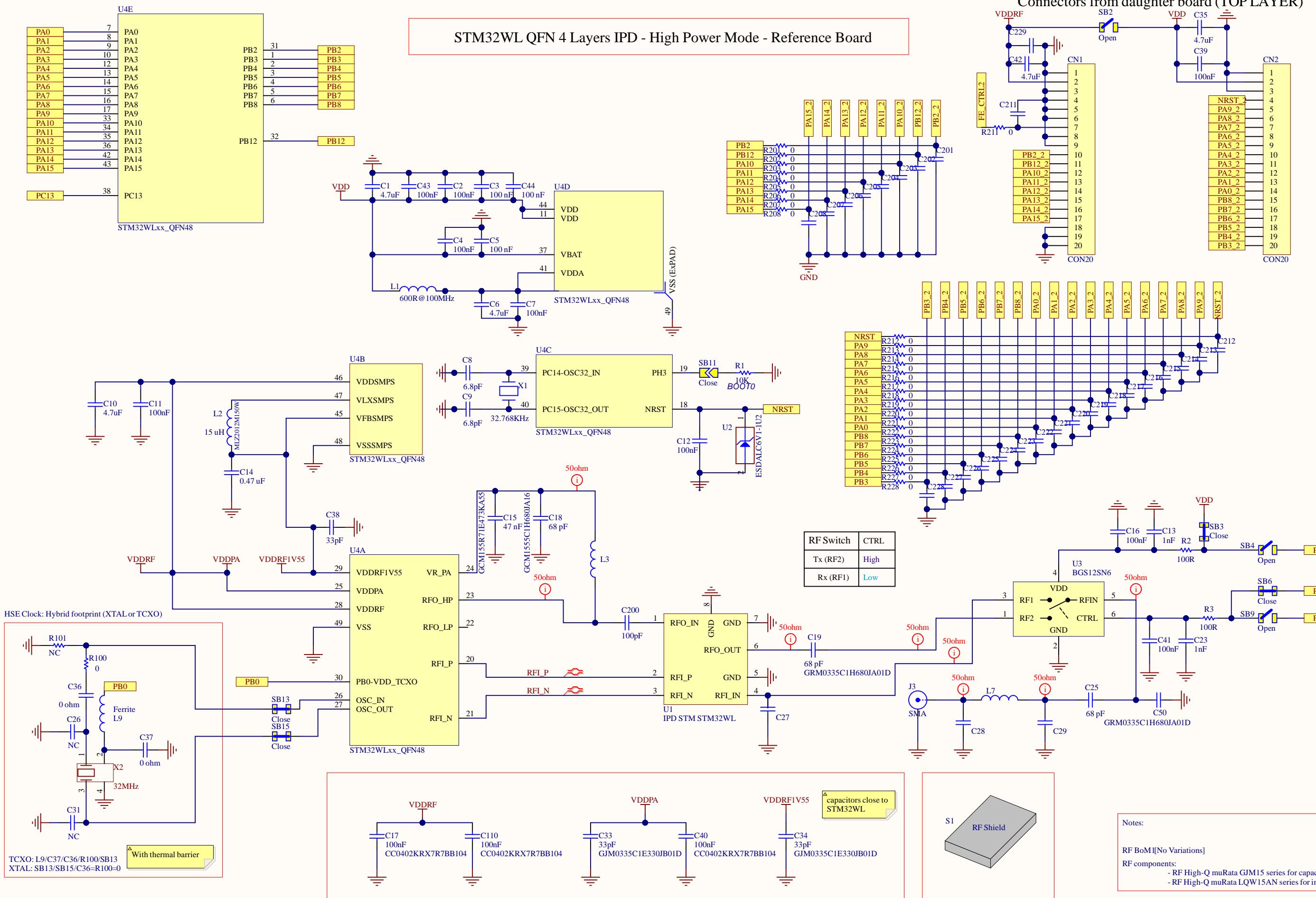
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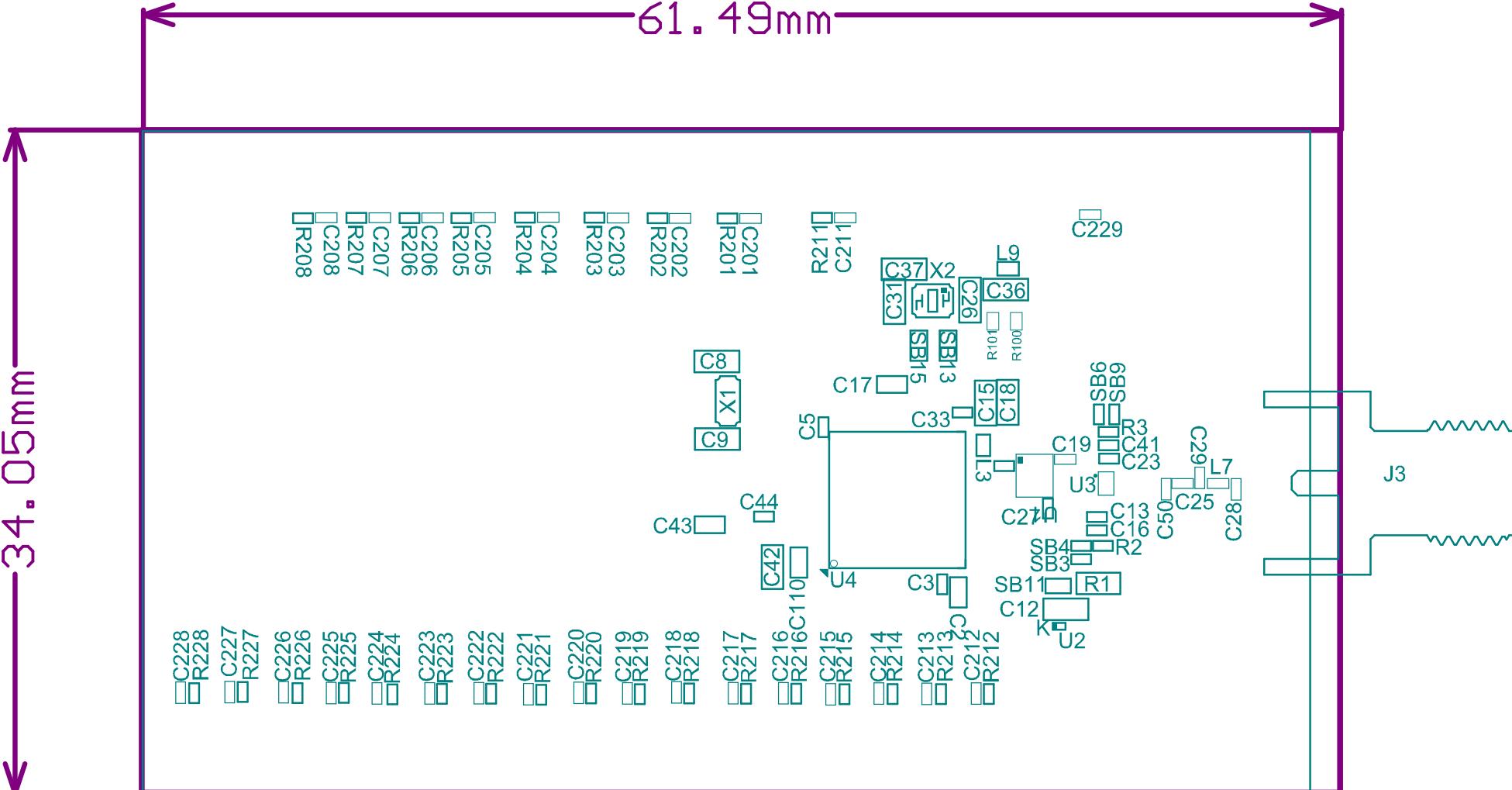
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[Reference_Design_STM32WL_4L_IPD_ST_HP.SchDoc](#)



Title: Schematic sheet title to update		
Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Variant: [No Variations]		
Revision: A-01	Reference: MB1848_HP	
Size: A4	Date: June 2022	Sheet: 1 of 2







Project: STM32WL_QFN48_IPD_4Layers_IPD_TK_HighPower

Layer: Top Assembly

Gerber: .GM14

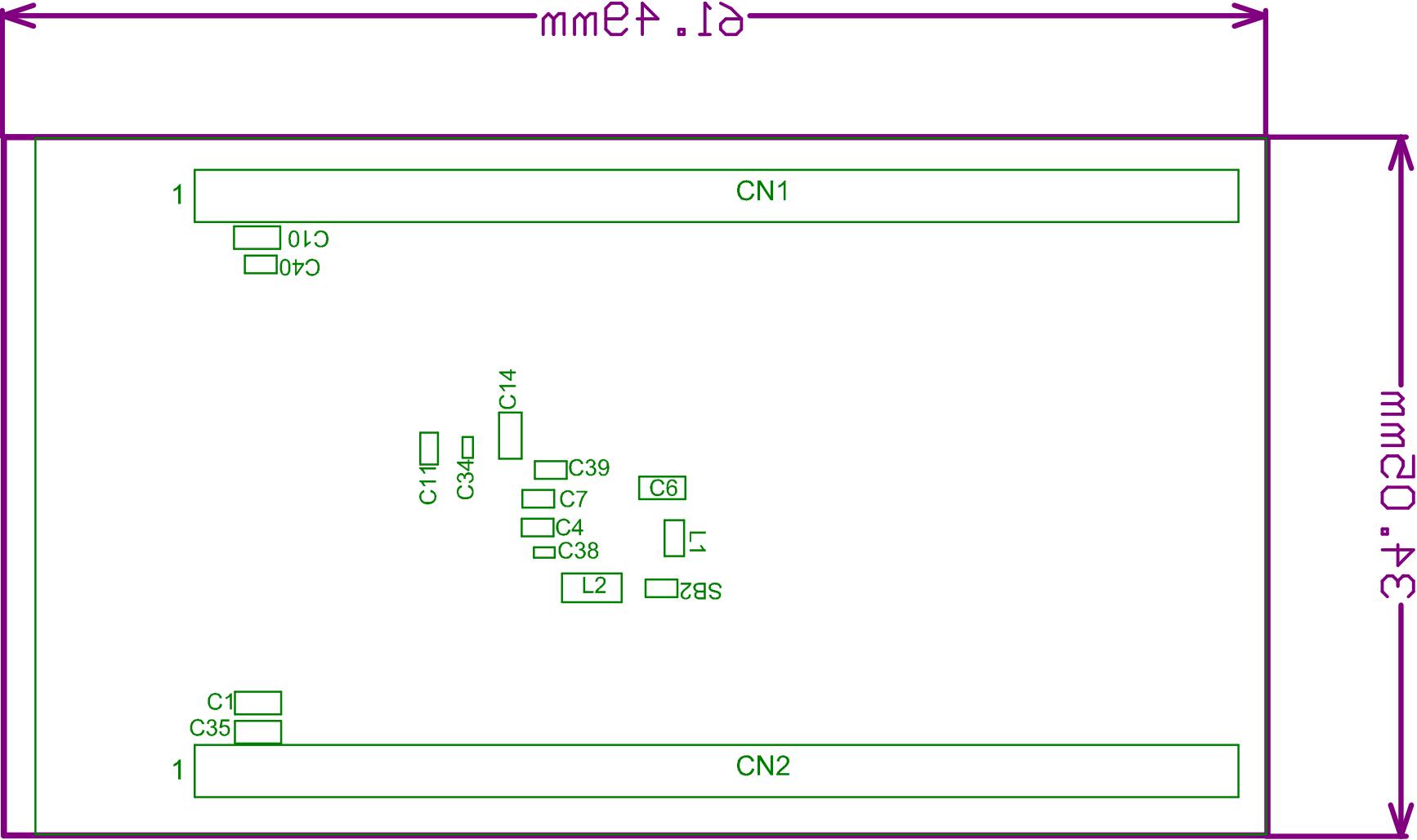
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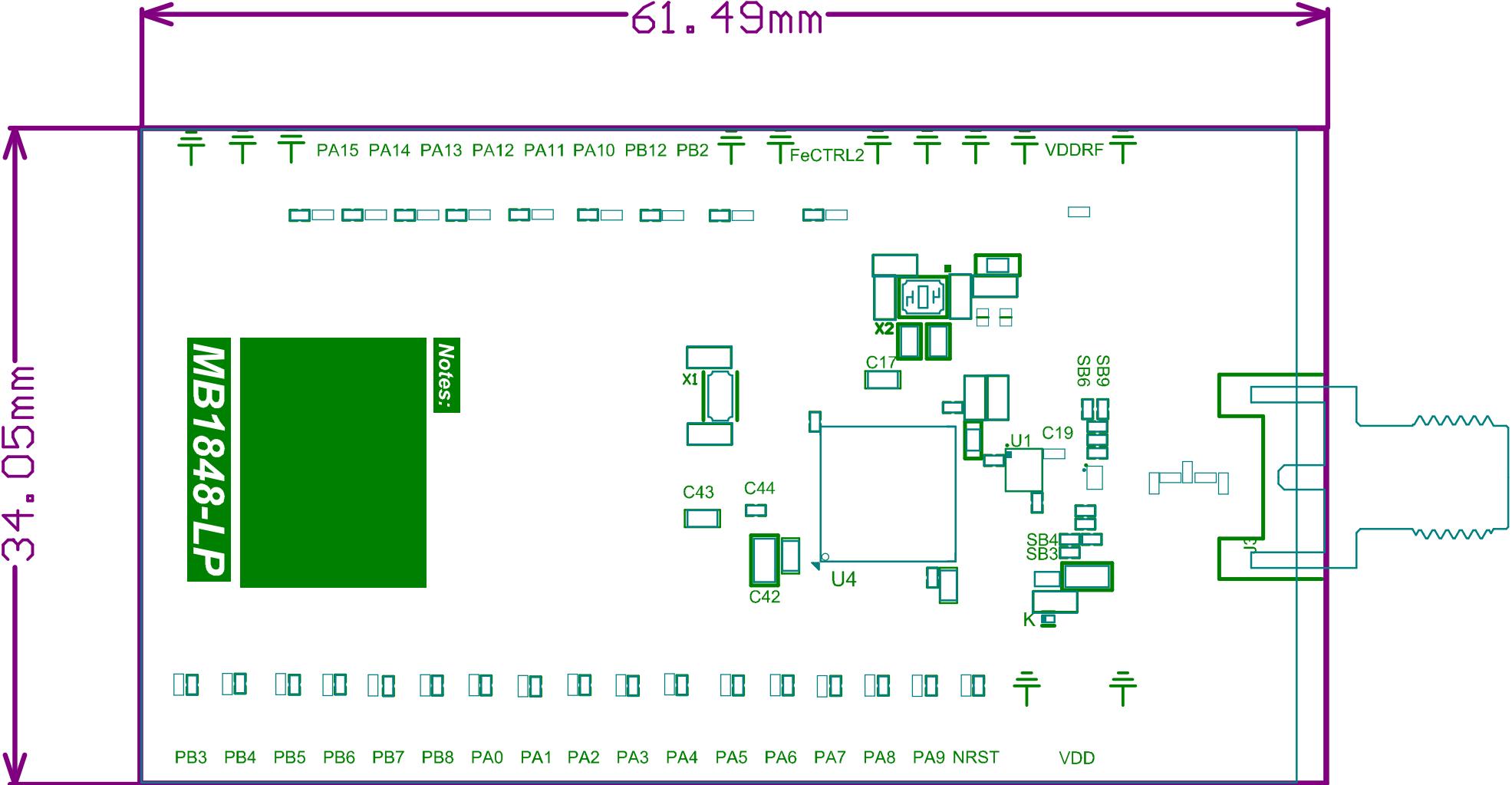
Ref: MB1848_HP

Date: June 2022

Rev: A







Top Assembly

.GM04

